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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/483,712	01/14/2000	Tongbi Jiang	3815US (98-0670)	8743

7590 09/06/2006  
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EXAMINER

WARREN, MATTHEW E

ART UNIT	PAPER NUMBER
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2815

DATE MAILED: 09/06/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

<b>Office Action Summary</b>	<b>Application No.</b> 09/483,712	<b>Applicant(s)</b> JIANG ET AL.	
	<b>Examiner</b> Matthew E. Warren	<b>Art Unit</b> 2815	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

#### Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

#### Status

- 1) ☒ Responsive to communication(s) filed on 19 June 2006.
- 2a) ☒ This action is **FINAL**.                      2b) ☐ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

#### Disposition of Claims

- 4) ☒ Claim(s) 1-16 and 19 is/are pending in the application.
- 4a) Of the above claim(s) \_\_\_\_\_ is/are withdrawn from consideration.
- 5) ☐ Claim(s) \_\_\_\_\_ is/are allowed.
- 6) ☒ Claim(s) 1-16 and 19 is/are rejected.
- 7) ☐ Claim(s) \_\_\_\_\_ is/are objected to.
- 8) ☐ Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

#### Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on \_\_\_\_\_ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.  
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

#### Priority under 35 U.S.C. § 119

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All    b) ☐ Some \*    c) ☐ None of:
- ☐ Certified copies of the priority documents have been received.
  - ☐ Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
  - ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

#### Attachment(s)

- |  |   |
|--|---|
| 1) <input type="checkbox"/> Notice of References Cited (PTO-892)   | 4) <input type="checkbox"/> Interview Summary (PTO-413)<br>Paper No(s)/Mail Date. _____ |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948)                                   | 5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152)             |
| 3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)<br>Paper No(s)/Mail Date _____ | 6) <input type="checkbox"/> Other: _____  |

## DETAILED ACTION

This Office Action is in response to the Amendment filed on June 19, 2006.

### ***Claim Rejections - 35 USC § 103***

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

Claims 1, 2, 5-9, and 13-16, and 19 are rejected under 35 U.S.C. 103(a) as being unpatentable over King et al. (US 5,677,566) in view of Havens et al. (US Pub 2001/0011773 A1).

In re claims 1 and 2, King et al. shows (figs. 6-8) an intermediate structure in the fabrication of a chip scale package comprising: a semiconductor die (14) having an active surface having a plurality of bond pads (18) thereon; a dielectric element (16) having an upper surface and a lower surface, the lower surface of the dielectric element attached to a portion of the active surface of said-the semiconductor die; a plurality of conductive lead frame members (13) having inner ends laterally spaced from said the plurality of bond pads, each conductive lead frame member of the plurality of conductive lead frame members having an upper surface (12) and a lower surface, a portion of the lower surface of each conductive lead frame member of the plurality of conductive lead frame members being attached to a portion of the upper surface of the dielectric element (16) for connecting each conductive lead frame member of the plurality of

conductive lead frame members to the active surface of the semiconductor die; a plurality of discrete conductive bond members (22), at least one discrete conductive bond member of the plurality of conductive bond members connecting the inner end of each conductive lead frame member of said-the plurality of conductive lead frame members to at least one bond pad of the plurality of bond pads on the active surface of the semiconductor die; a plurality of conductive carrier bonds (28), at least one carrier bond of the plurality of conductive carrier bonds directly disposed on the upper surface of each conductive lead frame member of the plurality of conductive lead frame members at a location remote from the inner end thereof and extending transversely from the upper surface thereof. King shows all of the elements of the claims except the intermediate structure free of encapsulant material to be subsequently applied to the intermediate structure. Havens et al. discloses [0025-0028] a package process in which an intermediate structure in the fabrication of a chip scale structure comprises the intermediate structure being free of encapsulant. The circuit substrate, ILD layers, conductive layers, and external conductors (solder balls 6) are formed prior to the encapsulation process. The encapsulant material is formed last to reduce moisture and improve product yield. Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to modify the intermediate package structure of King by forming the intermediate structure free of encapsulant as taught by Havens to reduce the amount of moisture in the package during the subsequent encapsulation process and ultimately improving the device yield.

In re claim 5, King et al. shows (fig. 3) wherein the upper surface and lower surface of the dielectric element are attached respectively to a portion of the lower surface of each conductive lead frame member of the plurality of conductive lead frame members and a portion of the active surface of the semiconductor die connecting portions of said the plurality of conductive lead frame members and to portions of the active surface of the semiconductor die.

In re claims 6-9, and 13-16, and 19 King discloses (col. 3, lines 10-21) wherein the plurality of conductive lead frame members comprises a plurality of lead fingers. The plurality of conductive lead frame members comprises a conductive metal. The plurality of discrete conductive bond members comprises a conductive metal. The plurality of discrete conductive bond members comprises bond wires. The plurality of conductive carrier bonds includes metal. King also shows (fig. 4) that the plurality of conductive carrier bonds is selectively located on the upper surfaces of the plurality of conductive lead frame members forming an array over the active surface of the semiconductor die and that the plurality of conductive carrier bonds comprises solder balls.

In re claim 19, King shows (fig. 3) that each conductive carrier bond of the plurality of conductive carrier bonds further comprises an upper portion and a lower portion, the lower portion of a-each conductive carrier bond being attached to the upper surface of an associated conductive lead frame member of the plurality of conductive lead frame members. The encapsulating material is disposed only about the lower portions of the plurality of conductive carrier bonds.

Claims 3, 4, and 10-12 are rejected under 35 U.S.C. 103(a) as being unpatentable over King et al. (US 5,677,566) in view of Havens et al. (US Pub 2001/0011773 A1) as applied to claims 2 and 9 above and further in view of Lee et al. (US 5,894,107).

In re claims 3, 4, and 10-12, King does not specifically disclose the materials of the dielectric element, the materials of the bond wires, or the types of conductive bond members, but such elements are not patentably distinguishable over the cited art because such materials are well known in the art. However, Lee et al. discloses a (col. 4, line 60 – col. 5, line 20) a chip scale package in which a dielectric element may be any adhesive including polyamide tape or films. The conductive bond members may comprise any conventional connecting members including metal, wires, gold, TAB or thermocompression bonds. Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to modify the materials of King and Havens by using specific materials of polyimide for the dielectric element, gold wires, and TAB or thermocompression bonds for the discrete conductive bond members as taught by Lee to provide well known, suitable conductor connections to form the chip scale package.

### ***Response to Arguments***

Applicant's arguments filed with respect to claims 1-16, and 19 have been fully considered but they are not persuasive. The applicant primarily asserts that one of ordinary skill in the art would not be motivated to combine the intermediate structure of

Havens with King and therefore, the combined references do not show all of the elements of the claims. The examiner maintains that the motivation to combine is proper and that the combined references show all of the elements of the claims. As stated in the rejection above and as argued by the applicant, King's intermediate structure is formed without the carrier bond. The intermediate structure of the applicant's invention is defined as the structure of the device prior to the final encapsulation process. King's device forms the carrier bond after the device is encapsulated, therefore King lacks the carrier bond in the intermediate structure. Havens was cited to cure the deficiencies of King by teaching an intermediate structure having the carrier bond formed on the conductive lead prior to the final encapsulation process. The electronic package (1) shown in figure 1 has the device formed on carrier/board (3) with solder balls (6) formed on their respective lead members/pads. Then the package (1) is immersed in a solution (2) to form the protective covering over the device [0028, specifically lines 1-10]. Havens discloses [0025-0026] that forming the intermediate structure in this manner allows the package to be subsequently sealed without moisture, thus improving the reliability and product yield. Although Havens discloses in another embodiment that the hydrophobic covering (23) can be applied prior to forming the external electrodes (6), it does not take away from the desirability to form the external electrodes before forming the hydrophobic covering. If forming the external electrodes first was not part of the improvement of reducing moisture, then why even cite that embodiment at all? At the very least Havens discloses [0026] that in one embodiment, all of the package, including all external conductor surfaces, are covered (e.g., to facilitate shipment). Thus,

Havens at least teaches that the external conductors are formed prior to encapsulation to facilitate shipment of the package. One of ordinary skill in the art would be motivated to improve King by using the inventive structure of Havens to improve the reliability and product yield or facilitate shipment. Havens shows some form of motivation for the improvement and the combined references show all of the elements of the claims. Therefore this action is made final.

### ***Conclusion***

**THIS ACTION IS MADE FINAL.** Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire **THREE MONTHS** from the mailing date of this action. In the event a first reply is filed within **TWO MONTHS** of the mailing date of this final action and the advisory action is not mailed until after the end of the **THREE-MONTH** shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than **SIX MONTHS** from the mailing date of this final action.

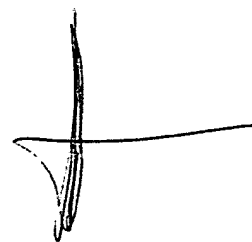
Any inquiry concerning this communication or earlier communications from the examiner should be directed to Matthew E. Warren whose telephone number is (571) 272-1737. The examiner can normally be reached on Mon-Thur and alternating Fri 9:00-5:00pm.



If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Kenneth Parker can be reached on (571) 272-2298. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

MEW  
*MEW*  
September 3, 2006

A handwritten signature in black ink, appearing to be 'K Parker', with a long horizontal line extending to the right.

KENNETH PARKER  
SUPERVISORY PATENT EXAMINER